



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



企业QQ二维码

Features

- $BV_{CEO} > -20V$
- $BV_{ECO} > -4V$
- $I_C = 8A$ High Continuous Current
- Low Saturation Voltage $V_{CE(sat)} < -47mV @ 1A$
- $R_{CE(sat)} = 28m\Omega$
- Complementary PNP Type: NK-ZXTN19020DG

Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound;
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.112 grams (Approximate)

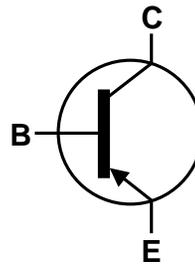
Applications

- Motor Drive
- Relay, Lamp and Solenoid Drive

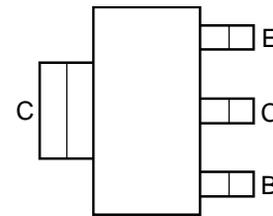
SOT223



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-25	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Collector Voltage (reverse blocking)	V _{ECO}	-4	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	I _C	-8	A
Base Current	I _B	-1	A
Peak Pulse Current	I _{CM}	-15	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

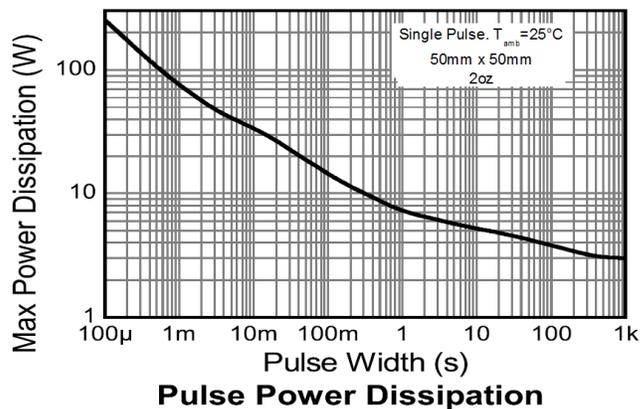
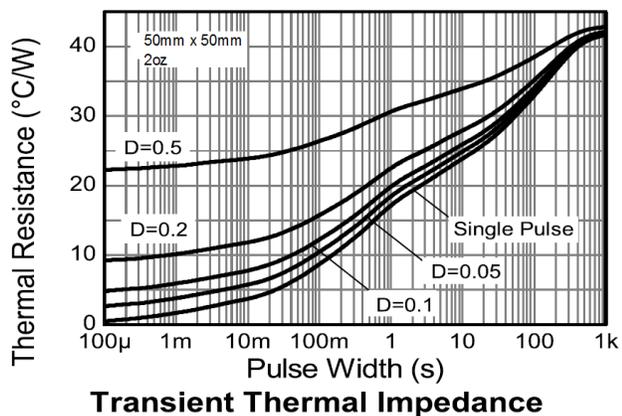
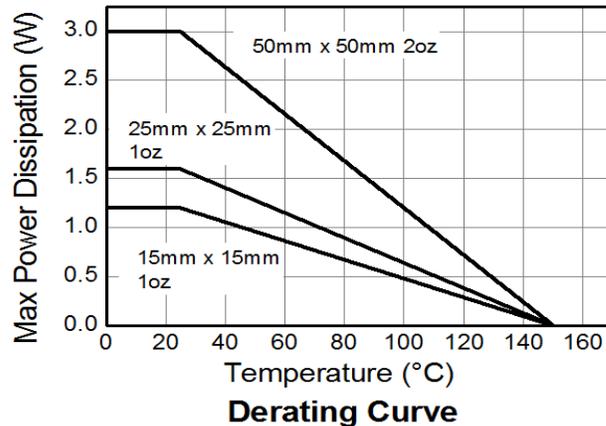
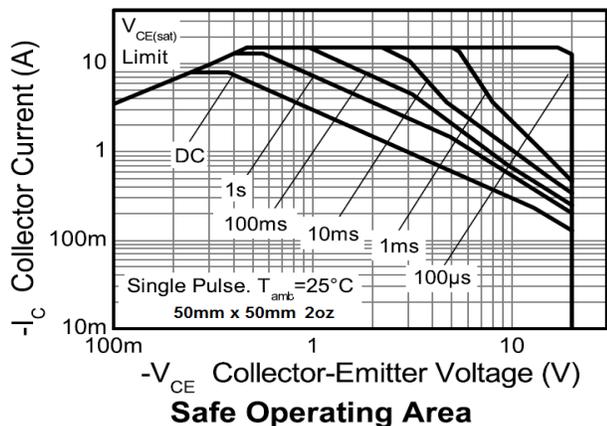
Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	P _D	1.2	W mW/°C
		9.6	
		1.6	
		12.8	
		3	
Thermal Resistance, Junction to Ambient	R _{θJA}	24	°C/W
		5.3	
		42	
		104	
Thermal Resistance, Junction to Lead	R _{θJL}	78	°C/W
		42	
		23.5	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 10)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the collector lead on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady-state.
 6. Same as Note 5, except the device is mounted on 25mm x 25mm 1oz copper.
 7. Same as Note 5, except the device is mounted on 50mm x 50mm 2oz copper.
 8. Same as Note 5 measured at t<5 seconds.
 9. Thermal resistance from junction to solder-point (at the end of the collector lead).
 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

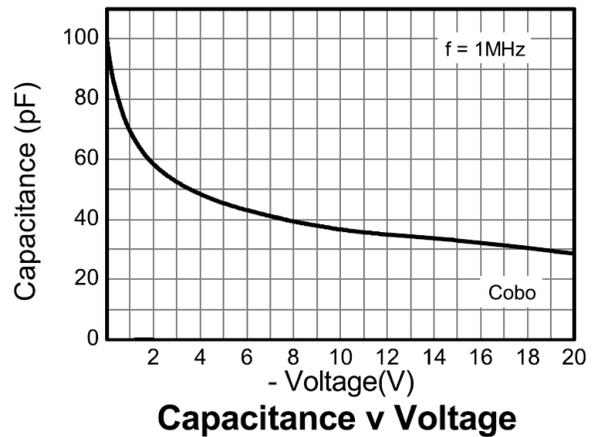
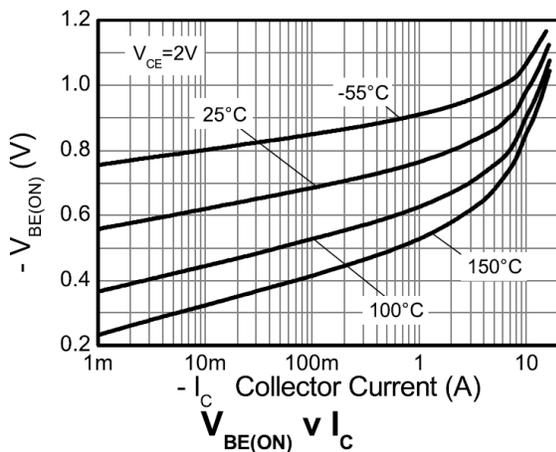
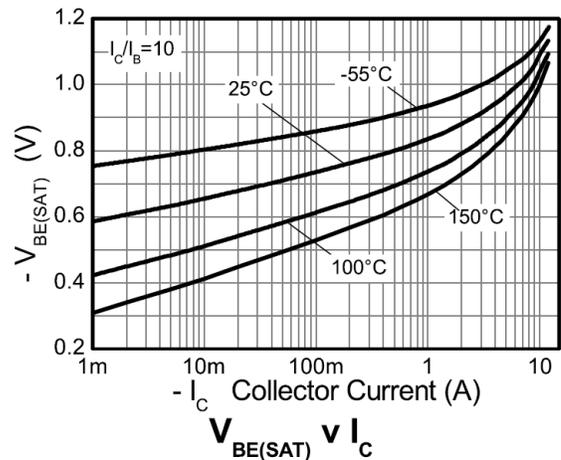
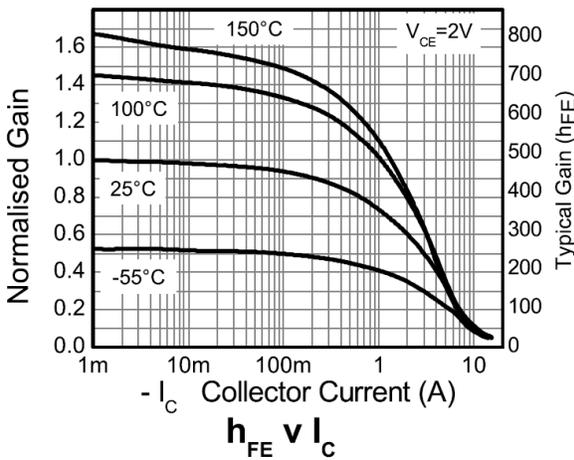
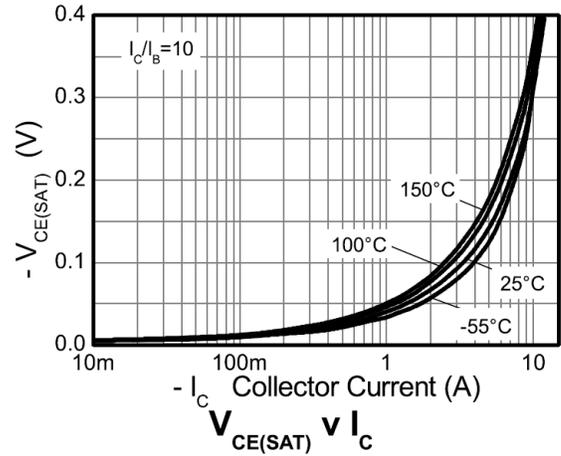
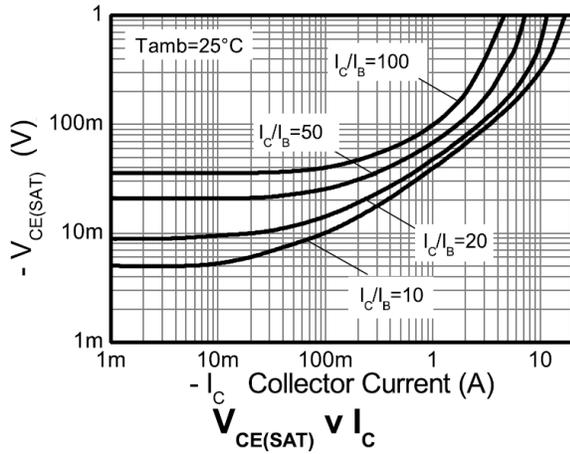


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

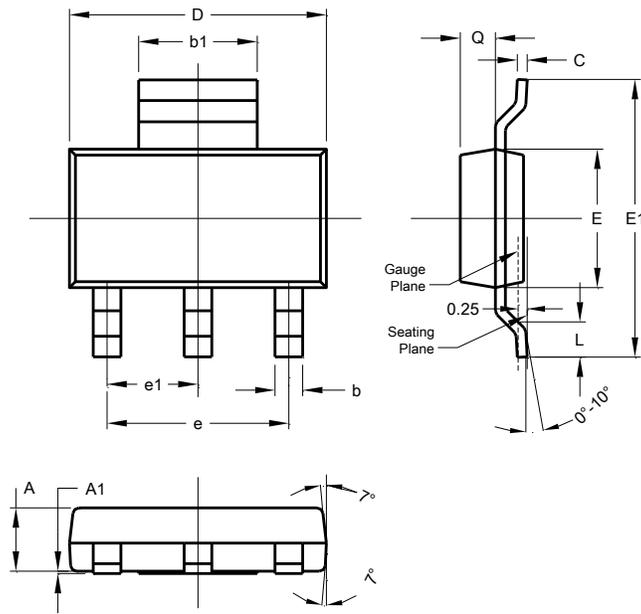
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	-25	-55	-	V	$I_C = -100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 11)	BV_{CEO}	-20	-50	-	V	$I_C = -10\text{mA}$
Emitter-Collector Breakdown Voltage (reverse blocking)	BV_{ECX}	-4	-8.6	-	V	$I_C = -100\mu\text{A}$, $R_{BC} < 1\text{k}\Omega$ or $0.25\text{V} < V_{BC} > -0.25\text{V}$
Emitter-Collector Breakdown Voltage (reverse blocking)	BV_{ECO}	-4	-8.6	-	V	$I_E = -100\mu\text{A}$
Emitter-Base Breakdown Voltage	BV_{EBO}	-7	-8.2	-	V	$I_E = -100\mu\text{A}$
Collector Cut-Off Current	I_{CBO}	-	< 1	-50	nA	$V_{CB} = -25\text{V}$
		-	-	-0.5	μA	$V_{CB} = -25\text{V}$, $T_A = +100^\circ\text{C}$
Emitter Cut-Off Current	I_{EBO}	-	< 1	-50	nA	$V_{EB} = -5.6\text{V}$
Collector-Emitter Saturation Voltage (Note 11)	$V_{CE(sat)}$	-	-40	-47	mV	$I_C = -1\text{A}$, $I_B = -100\text{mA}$
		-	-97	-130	mV	$I_C = -1\text{A}$, $I_B = -10\text{mA}$
		-	-115	-145	mV	$I_C = -2\text{A}$, $I_B = -40\text{mA}$
		-	-220	-275	mV	$I_C = -8\text{A}$, $I_B = -800\text{mA}$
Base-Emitter Saturation Voltage (Note 11)	$V_{BE(sat)}$	-	-1050	-1150	mV	$I_C = -8\text{A}$, $I_B = -800\text{mA}$
Base-Emitter Turn-On Voltage (Note 11)	$V_{BE(on)}$	-	-930	-1000	mV	$I_C = -8\text{A}$, $V_{CE} = -2\text{V}$
DC Current Gain (Note 11)	h_{FE}	300	450	900	-	$I_C = -100\text{mA}$, $V_{CE} = -2\text{V}$
		200	290	-	-	$I_C = -2\text{A}$, $V_{CE} = -2\text{V}$
		45	70	-	-	$I_C = -8\text{A}$, $V_{CE} = -2\text{V}$
		-	25	-	-	$I_C = -15\text{A}$, $V_{CE} = -2\text{V}$
Current Gain-Bandwidth Product (Note 11)	f_T	-	176	-	MHz	$V_{CE} = -10\text{V}$, $I_C = -50\text{mA}$, $f = 50\text{MHz}$
Input Capacitance (Note 11)	C_{ibo}	-	-	400	pF	$V_{EB} = -0.5\text{V}$, $f = 1\text{MHz}$
Output Capacitance (Note 11)	C_{obo}	-	36	45	pF	$V_{CB} = -10\text{V}$, $f = 1\text{MHz}$
Delay Time	t_d	-	23	-	ns	$I_C = -1\text{A}$, $V_{CC} = -10\text{V}$, $I_{B1} = -I_{B2} = -50\text{mA}$
Rise Time	t_r	-	18.4	-	ns	
Storage Time	t_s	-	266	-	ns	
Fall Time	t_f	-	49.6	-	ns	

 Note: 11. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

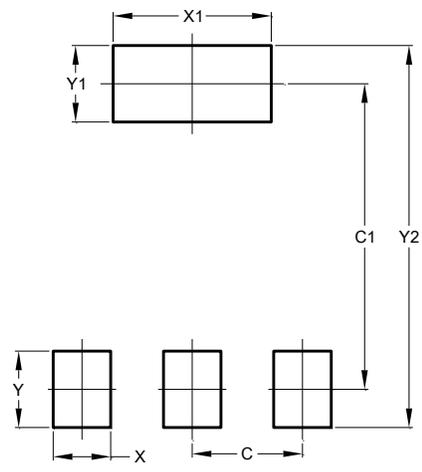


Package Outline Dimensions



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00